

SPECIFICATION AMENDMENTS

Amendments to the paragraph beginning at page 8, line 4:

wherein each of R1, R2, and R3, which may be the same or different, each is an aryl group, a hydrogen atom, an aliphatic alkyl group, a hydroxyl group, trialkylsilyl group, or a functional group having an unsaturated bond, and each of l, m, and n each is integers of 0 or more, an integer and $l + m + n \geq 1$, and the silicone polymer has a weight average molecular weight of not less than 1000.

Amendments to the paragraph beginning at page 8, line 11:

wherein each of R1 and R2, which may be the same or different, each is an aryl group, a hydrogen atom, an aliphatic alkyl group, or a functional group having an unsaturated bond. Notations Each of R3, R4, R5, and R6, which may be the same or different, each is a hydrogen atom, an aryl group, an aliphatic alkyl group, a trialkylsilyl group, or a functional group having an unsaturated bond, n is an integer and at least 1, and the silicone polymer has a weight average molecular weight of not less than 1000.

Amendments to the paragraph beginning at page 25, line 22:

An acceleration sensor according to the invention ~~is provided with~~ includes a silicon substrate 42 in ~~a~~ the shape of a frame ~~formed~~ along a periphery of a glass substrate 41, a sensing portion 43 ~~projected~~ projecting from the silicon substrate 42 above a plane ~~extended~~ with ~~at~~ a constant ~~interval~~ distance from the glass substrate 41, and an opposed electrode 44, ~~contiguously arranged~~ contiguous to the sensing portion ~~43~~ 43, ~~capable of~~ capable of 43, forming an electric capacitance between opposed side faces of the opposed electrode 44 and the sensing portion 43. Further, a surface and side faces of the sensing portion ~~42 to 43 are~~ 42 to 43 are covered with a silicone resin film 45. ~~There are provided bonding~~ Bonding pads 46 and 47 are used for ~~respectively~~ detecting the electric capacitance ~~above~~ between the silicon substrate 42 ~~in~~ having the frame shape and the opposed electrode 44. Further, contact holes 48 and 49 are ~~provided~~ located at portions of the glass substrate ~~above~~ opposite the bonding pads 46 and 47.